

Part Number: XZFAMOK10A

SURFACE MOUNT DISPLAY

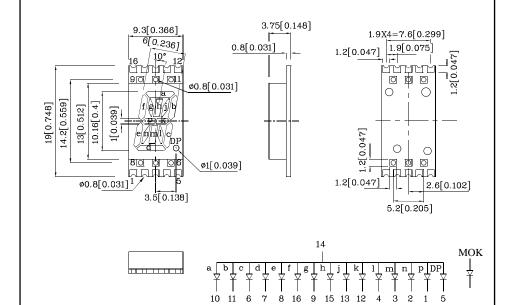
Features

- 0.4 inch digit height
- Robust package
- Low power consumption
- \bullet Standard configuration: Gray face w/ white segments
- Standard Package: 400pcs/ ReelMSL (Moisture Sensitivity Level): 2a
- RoHS compliant





Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 2. Specifications are subject to change without notice.
- 3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T _A =25°C)		MOK (AlGaInP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	195	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		

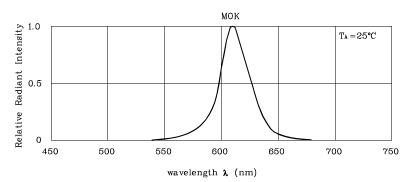
Operating Characteristics (T _A =25°C)	MOK (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ 610*		nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	601*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	29	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	$\begin{array}{c} Luminous\ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}10\text{mA}) \\ ucd \end{array}$	Wavelength CIE127-2007* nm λP	Description
			min. typ.		
XZFAMOK10A	Orange	AlGaInP	21000 43990 5600* 12990*	610*	Common Anode, Rt.Hand Decimal.

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Jan 14,2014

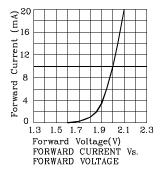


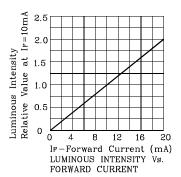


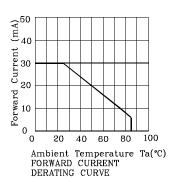


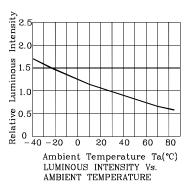
RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ MOK



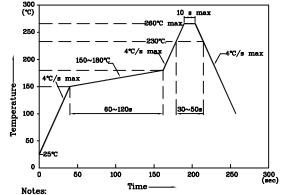






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

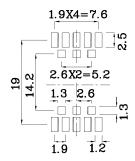


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

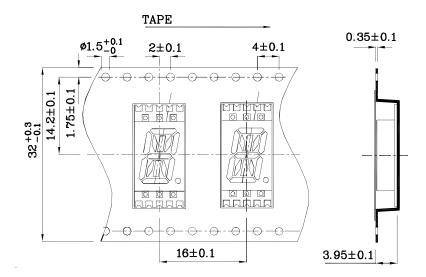
www.SunLEDusa.com

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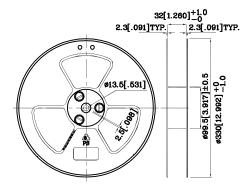
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ±0.15)



❖ Tape Specification (Units:mm)



* Reel Dimension



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

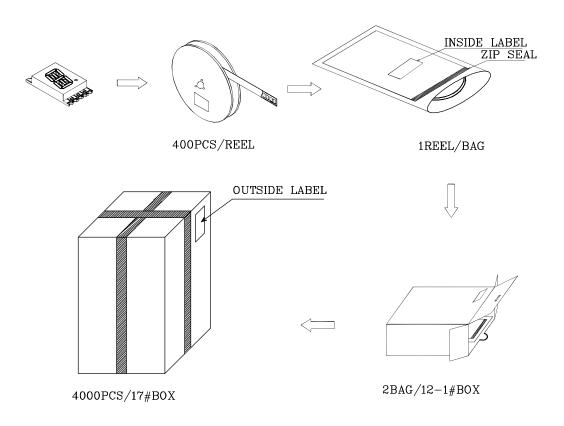
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

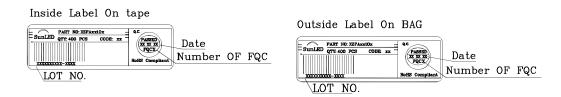
Note: Accuracy may depend on the sorting parameters.

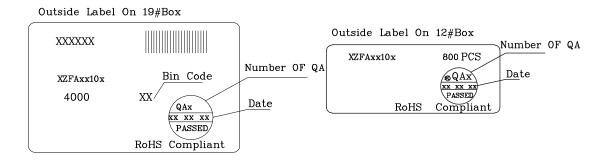




PACKING & LABEL SPECIFICATIONS







TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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